

Notice of References Cited	Application/Control No. 09/808,786	Applicant(s)/Patent Under Reexamination HEAVLIN, WILLIAM D.	
	Examiner Russell Frejd	Art Unit 2128	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,567,717	05-2003	Krivokapic et al.	700/121
	B	US-6,389,366	05-2002	Heavlin, William D.	702/84
	C	US-6,304,836	10-2001	Krivokapic et al.	703/14
	D	US-5,966,527	10-1999	Krivokapic et al.	703/14
	E	US-5,724,251	03-1998	Heavlin, William D.	716/5
	F	US-5,655,110	08-1997	Krivokapic et al.	716/19
	G	US-5,646,870	07-1997	Krivokapic et al.	716/4
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	KRIVOKAPIC et al., Z. Intrafield Effects and Device Manufacturability: A Statistical Simulation Approach, IEEE, #rd International Workshop on Statistical Metrology, June 1998, pages 36-9.
	V	HEAVLIN, W.D. First Silicon Experiments Within Wafers, 1999 IEEE International Symposium on Semiconductor Manufacturing, October 1999, pages 375-8.
	W	YUN et al., I. Parametric Manufacturing Yield Modeling og GaAs/A1GaAs Multiple Quantum Well Avalanche Photodiodes, IEEE Transactions on Semiconductor Manufacturing, Vol. 12, No. 2, May 1999, pages 238-51.
	X	GIBSON et al., D. Statistically Based Parametric Yield Prediction for Integrated Circuits, IEEE Transactions on Semiconductor Manufacturing, Vol. 10, No. 4, November 1997, pages 445-58.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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